





# 目录

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## 1、特点 Features

- ◆ EMC 封装，高亮度，高可靠性，主要用于汽车应用  
EMC package ,High brightness ,High efficiency ,It is mainly used in automobile applications
- ◆ 尺寸：2.7mm\*2.0mm\*0.6mm  
Size: 2.7mm\*2.0mm\*0.6mm
- ◆ 根据白光标准分档  
According to standard white color gamut
- ◆ 通过 RoHS 认证  
RoHS compliant
- ◆ MSL 等级 2a  
MSL 2a
- ◆ 适于 SMT 贴片  
Compatible with SMT
- ◆ 发光角度：120°  
Viewing Angle: 120°
- ◆ 包装：最大 3000 颗/卷  
Package: Max: 3000pcs /reel
- ◆ 建议额定使用电流为 200mA  
Recommended current 200mA
- ◆ 通过 AEC-Q102  
AEC-Q102 Qualified

## 2、应用 Applications

汽车内外部照明

Interior and exterior lighting for automotive





### 3、性能 Performance

#### a) 极限参数 Maximum Ratings

| 参数<br>Parameter                                 | 符号<br>Symbol | 数值<br>Rating                                 | 单位<br>Unit |
|---|--------------|--|------------|
| 最大正向电流<br>Max DC Forward Current                | $I_F$        | 250  | mA         |
| 功率<br>Power Dissipation                         | P            | 0.7  | W          |
| 峰值正向电流<br>Peak Forward Current                  | $I_{FP}$     | 700  | mA         |
| 最大反向电压<br>Maximum Reverse Current               |              | 不可施加反向电压<br>Do not apply for reverse current |            |
| 结温 (DC 模式)<br>LED Junction Temperature(DC mode) | $T_j$        | 150  | °C         |
| 工作温度<br>Operating Temperature Range             | $T_{opr}$    | -40~125                                      | °C         |
| 存储温度<br>Storage Temperature                     | $T_{stg}$    | -40~125                                      | °C         |
| ESD (人体模式)<br>ESD Human Body Mode               | ----         | 8000   | V          |

备注 Notes :

◇ 绝对最大额定值环境温度  $T_a=25^{\circ}\text{C}$

Absolute Maximum Ratings at  $T_a=25^{\circ}\text{C}$

◇  $I_{FP}$  脉冲时间 $\leq 10\text{ms}$ ，宽度 $\leq 10\%$

$I_{FP}$  Conditions with pulse width  $\leq 10\text{ms}$  and duty cycle $\leq 10\%$

b) 光电参数 Electro-Optical Characteristics (T solder pad =25 °C, I<sub>F</sub> =200mA)

| 项目<br>Item   | 符号<br>Symbol            | 最小值<br>Min. | 典型值<br>Typ. | 最大值<br>Max. | 单位<br>Unit |
|--|-------------------------|-------------|-------------|-------------|------------|
| 光通量<br>Luminous Flux   | Φ                       | 60          | 70          | 100         | Lm         |
| 正向电压<br>Forward Voltage  | V <sub>F</sub>          | 2.75        | 3.0         | 3.50        | V          |
| 色坐标<br>Color Coordinate  | X                       | --          | 0.323       | --          |            |
|  | Y                       | --          | 0.335       | --          |            |
| 显指<br>Ra   | R <sub>a</sub>          | 60          |             |             |            |
| 反向电流<br>Reverse Current (V <sub>R</sub> =5V)                             | I <sub>R</sub>          | --          | --          | 1           | uA         |
| 实际热阻 PN/焊点<br>Real Thermal Resistance<br>(Junction to Solder point)      | R <sub>thJS real</sub>  |             | 20          | 22          | °C/W       |
| 电热阻 PN/焊点<br>Electrical Thermal Resistance<br>(Junction to Solder point) | R <sub>thJS elec.</sub> |             | 15          | 18          | °C/W       |
| 发光角度<br>Viewing Angle  | 2θ                      |             | 120         |             | °          |

备注 Notes :

◇ 光通量测量误差范围±6%

Luminous flux measurement tolerance: ±6%

◇ 光电参数测试是瞬态时间为 20ms

Electric and optical data is tested at 20 ms pulse condition

c) 亮度分布特性 **Luminous Flux Characteristics** (T solder pad = 25 °C, I<sub>F</sub> =200mA)

| Product | Normal CCT | Chromaticity | Minimum Luminous Flux |       | Order Code (e. g.) |
|---------|------------|--------------|-----------------------|-------|--------------------|
|         |            |              | Code                  | Value |                    |
| N3      | 5400~5850  | CW           | C1                    | 60    | N3-B-CW-C1-DD7     |
|         |            |              | D1                    | 70    |                    |
|         | 5600~6100  | CX           | C1                    | 60    | N3-B-CX-C1-DD7     |
|         |            |              | D1                    | 70    |                    |
|         | 5850~6350  | CY           | C1                    | 60    | N3-B-CY-C1-DD7     |
|         |            |              | D1                    | 70    |                    |
|         | 6100~6650  | CZ           | C1                    | 60    | N3-B-CZ-C1-DD7     |
|         |            |              | D1                    | 70    |                    |


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#### 4、产品代码 Product Order Code

N3 - B - CX - E1 - DD6  
 ①                      ②                      ③                      ④                      ⑤

- ① 产品型号      Product Type (N3:LWJ-01)
- ② 显色指数      Ra level
- ③ 色温区块      Color Area
- ④ 亮度等级      Brightness Level
- ⑤ 电压等级      VF Level

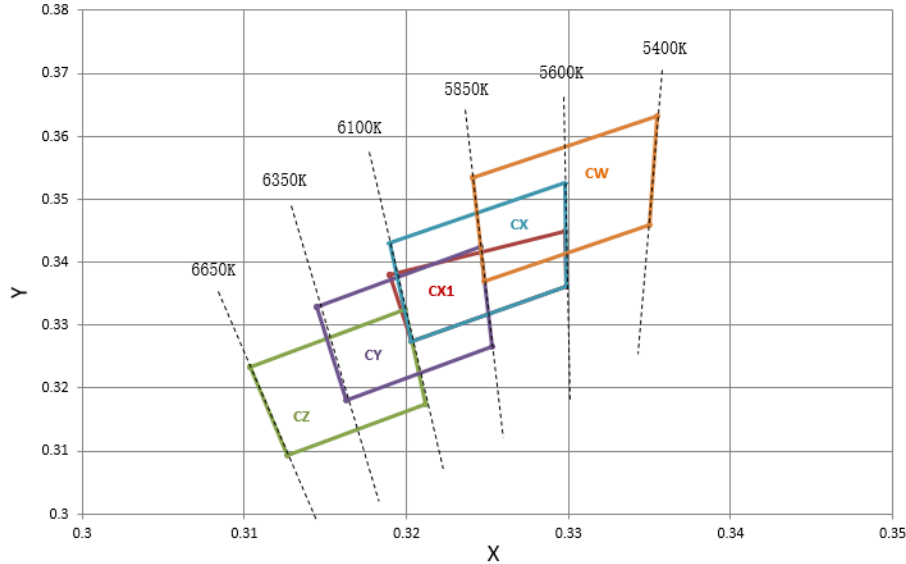
#### 出货标签(例) Shipping label (e.g.)



**LatticePower Corporation limited**  
 Item: N3-B-CX-E1-DD6 LWJ-01  
  
 MSL 2a Reel ID: AN3A00000001  
  
 Qty: 3000                      6N3XAAAA  
                      Date:2023-07-30

## 5、分档规则 Bin Regulations

### a) 色度区域 Chromaticity Regions (T solder pad = 25°C, I<sub>F</sub> = 200 mA)



**Color Chromaticity Groups**

| Color Bin          | x      | y      | Color Bin         | x      | y      |
|--------------------|--------|--------|-------------------|--------|--------|
| CW<br>5400K~5850K  | 0.3241 | 0.3534 | CY<br>5850K~6350K | 0.3145 | 0.3330 |
|                    | 0.3248 | 0.3370 |                   | 0.3163 | 0.3181 |
|                    | 0.3350 | 0.3460 |                   | 0.3246 | 0.3424 |
|                    | 0.3355 | 0.3633 |                   | 0.3253 | 0.3266 |
| CX<br>5600K~6100K  | 0.3190 | 0.3430 | CZ<br>6100K~6650K | 0.3104 | 0.3234 |
|                    | 0.3203 | 0.3274 |                   | 0.3127 | 0.3093 |
|                    | 0.3298 | 0.3526 |                   | 0.3199 | 0.3325 |
|                    | 0.3299 | 0.3361 |                   | 0.3212 | 0.3175 |
| CX1<br>5600K~6100K | 0.3190 | 0.3380 |                   |        |        |
|                    | 0.3203 | 0.3274 |                   |        |        |
|                    | 0.3299 | 0.3361 |                   |        |        |
|                    | 0.3298 | 0.3450 |                   |        |        |

备注 Notes :

◇ 色度坐标 (x, y) 来自 CIE1931 色度图

The chromaticity coordinates(x,y)is derived from the CIE 1931 chromaticity diagram

◇ PT86 测试设备用于光通量 (lm) 和 CIE1931 色度坐标 (x, y) 测试。

PT86 is for the luminous flux(lm) and the CIE1931 chromaticity coordinates(x,y) testing.

◇ 色度坐标 (x, y) 存在±0.006 公差。

The chromaticity coordinates(x,y) guarantee should be added ±0.006 tolerance.



**b) 亮度分档 Luminous Flux Groups (T solder pad = 25°C, I<sub>F</sub> =200 mA)**

| Group Code | Min. | Max. |
|------------|------|------|
| C1         | 60   | 70   |
| D1         | 70   | 80   |
| E1         | 80   | 90   |
| F1         | 90   | 100  |

**c) 电压分档 Voltage Groups (T solder pad = 25°C, I<sub>F</sub> =200 mA)**

| Group Code | Range     |
|------------|-----------|
| DD6        | 2.75~3.00 |
| DD7        | 3.00~3.25 |
| DD8        | 3.25~3.50 |

**d) 显指分档 Ra Groups (T solder pad = 25°C, I<sub>F</sub> =200 mA)**

| Group Code | Range  |
|------------|--------|
| B          | 60~100 |

备注 Notes :

- ◇ 亮度测试存在±6%的公差  
It maintains a tolerance of ±6% on luminous flux measurements.
- ◇ 电压测试误差±0.1V  
Forward voltage(VF) ±0.1V

## 6、光电特性图 The Photoelectric Characteristics Graph

Fig 1. 辐射特性 / Radiation Characteristics

IF=200mA; TS = 25°C

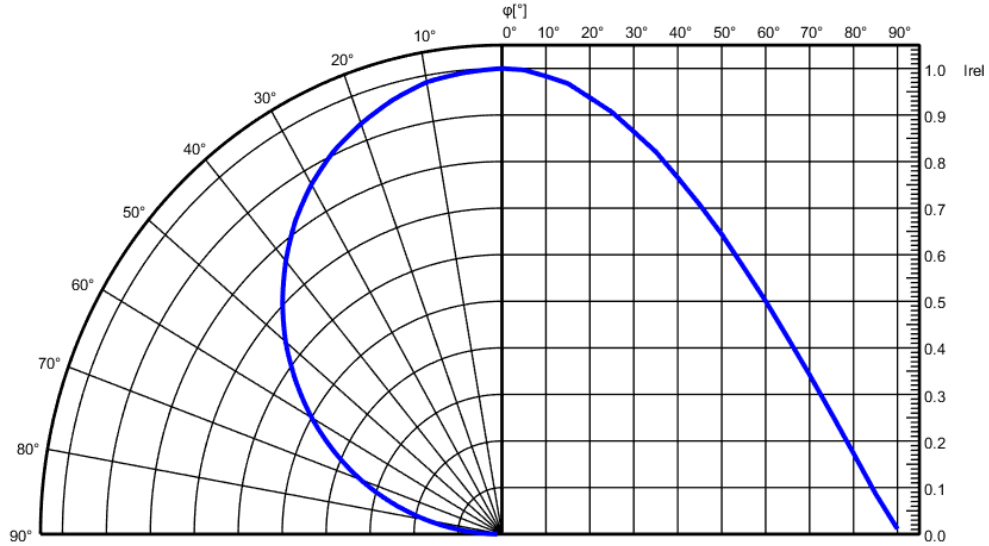
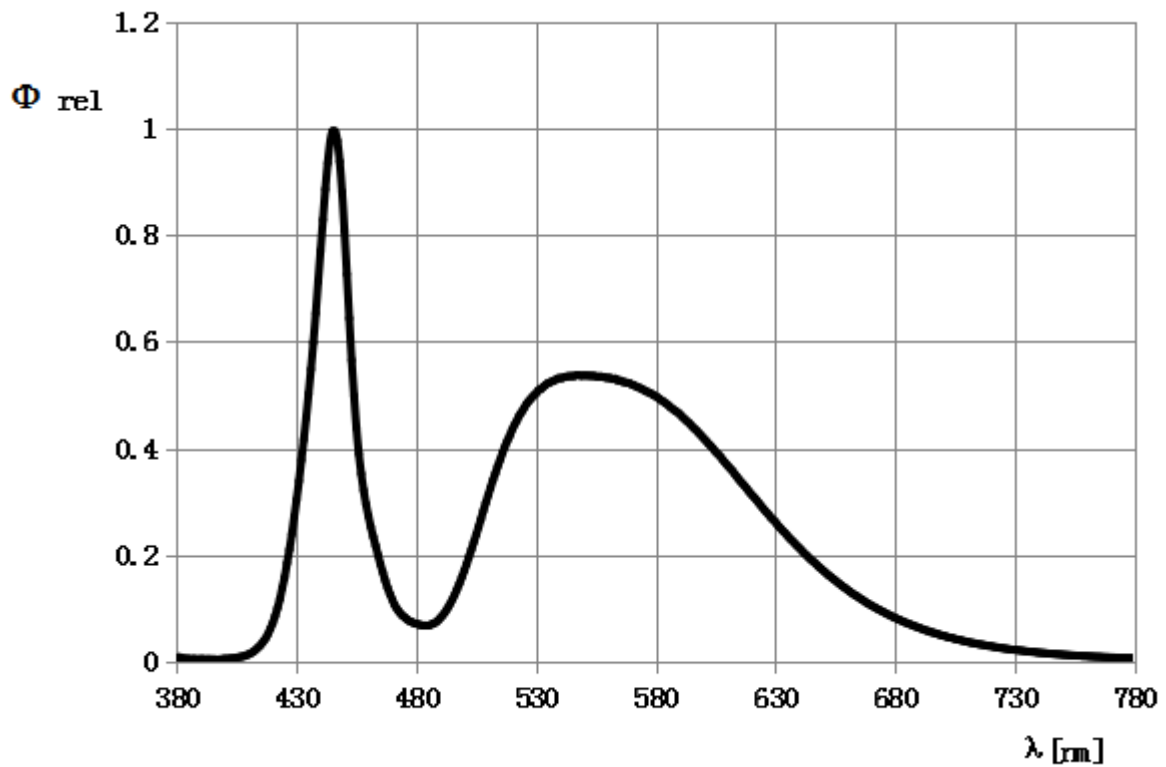


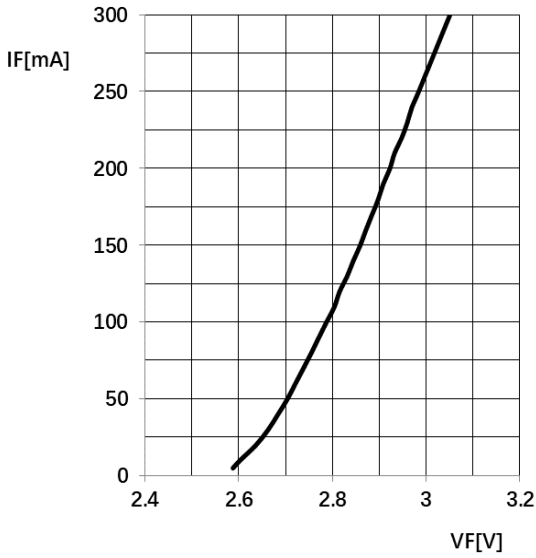
Fig 2. 相对发光光谱 / Relative Spectral Power Distribution vs. Wavelength

$\Phi_{rel}=f(\lambda)$ ; IF=200mA; TS = 25°C



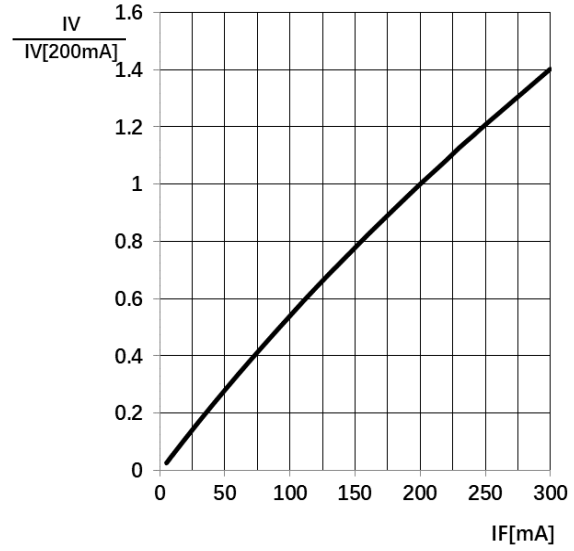
**Fig 3. 正向电流/Forward Voltage**

$I_F = f(V_F); TS = 25^\circ C$



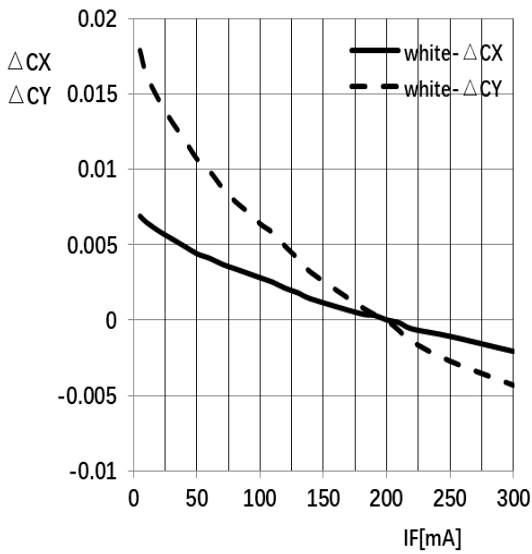
**Fig 4. 相对发光强度/Relative Luminous Intensity**

$I_v / I_v(200 \text{ mA}) = f(I_F); TS = 25^\circ C$



**Fig 5. 色坐标偏移/Chromaticity Coordinate Shift**

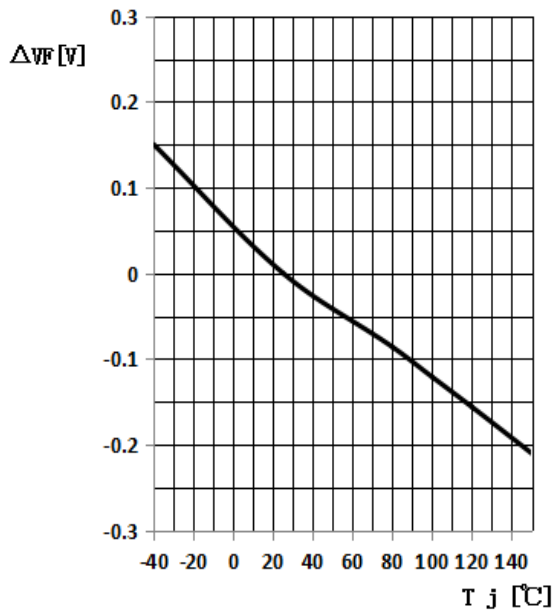
$\Delta C_x, \Delta C_y = f(I_F); TS = 25^\circ C$



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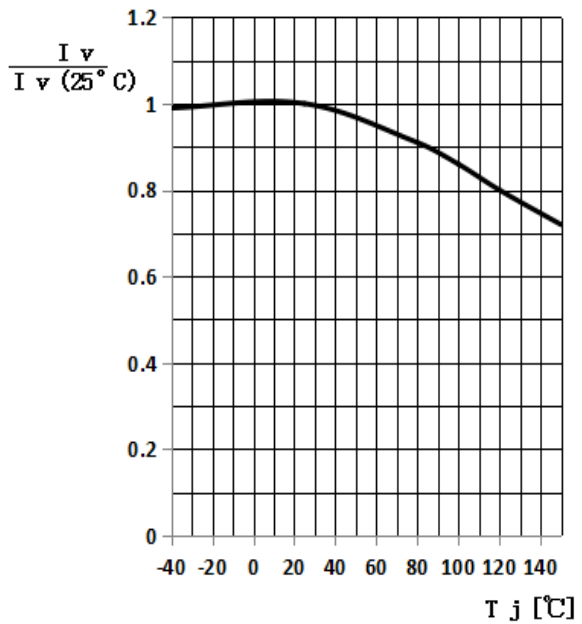
**Fig 6. 正向电压/Forward Voltage**

$\Delta VF = VF - VF(25^\circ C) = f(T_j); I_F = 200mA$



**Fig 7. 相对发光强度 Relative Luminous Flux**

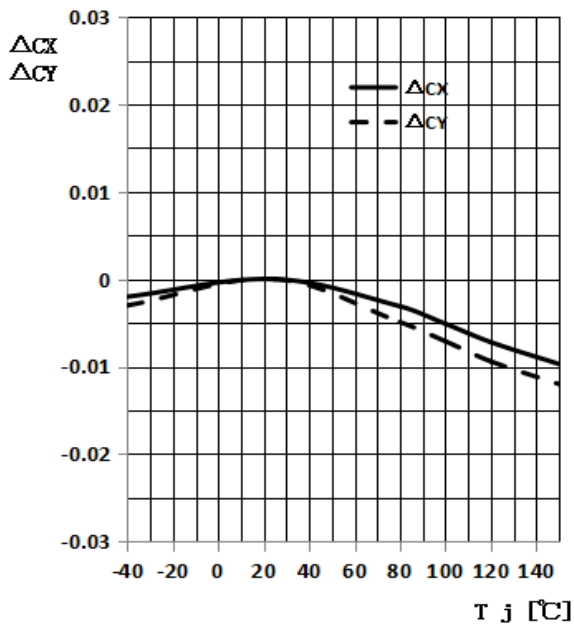
$I_v / I_v(25^\circ C) = f(T_j); I_F = 200mA$



**Fig 8. 色坐标偏移/**

**Chromaticity Coordinate Shift**

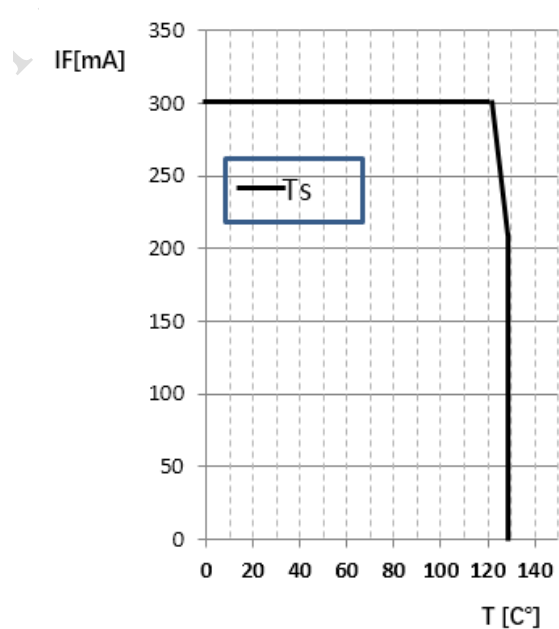
$\Delta C_x, \Delta C_y = f(I_F); T_S = 25^\circ C$



**Fig 9. 最大正向电流/**

**Max. Permissible Forward Current**

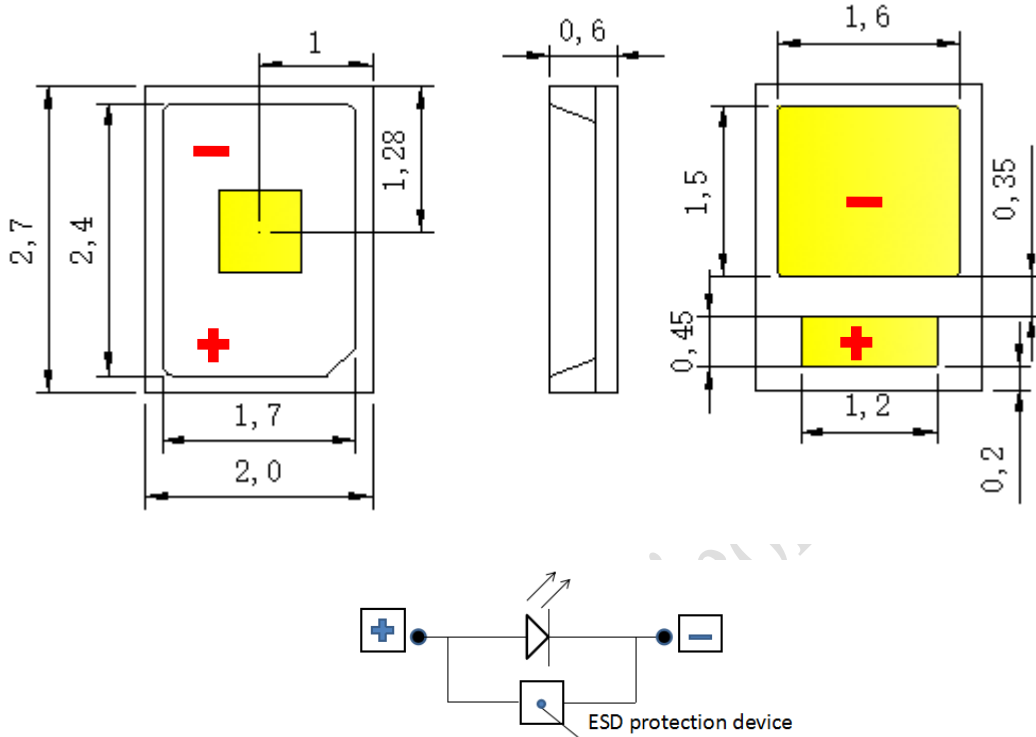
$I_F = f(T)$



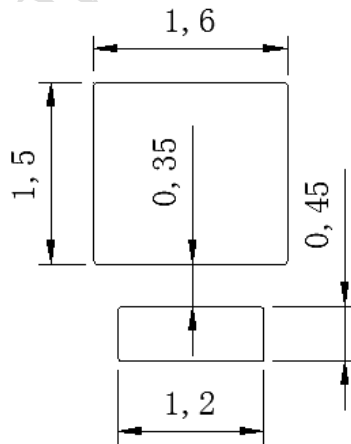


## 7、产品及钢网尺寸 Product and PCB Pad Dimensions

### a) 产品尺寸 Product Dimensions:



### b) 推荐焊盘尺寸/ PCB Pad Dimensions

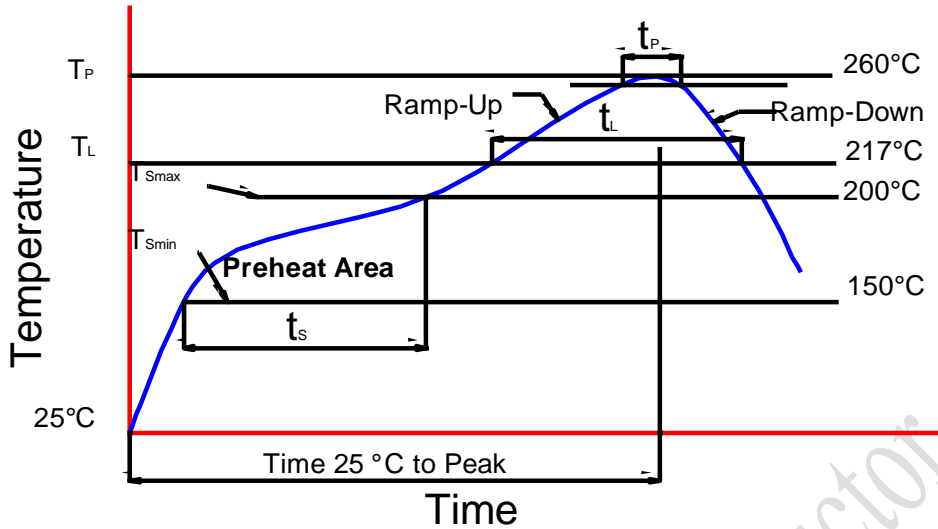


备注 Notes:

- ◇ 所有尺寸均以 mm 为单位  
All dimensions are in millimeters
- ◇ 尺寸未按照公差±0.1mm 标记的，按照图纸标记  
Size is not marked in accordance with tolerance ±0.1mm and dimension tolerances in accordance with drawings
- ◇ 灯珠近似重量: 10.6mg  
Approximate Weight: 10.6mg



## 8、回流焊特性 Reflow Soldering Characteristics

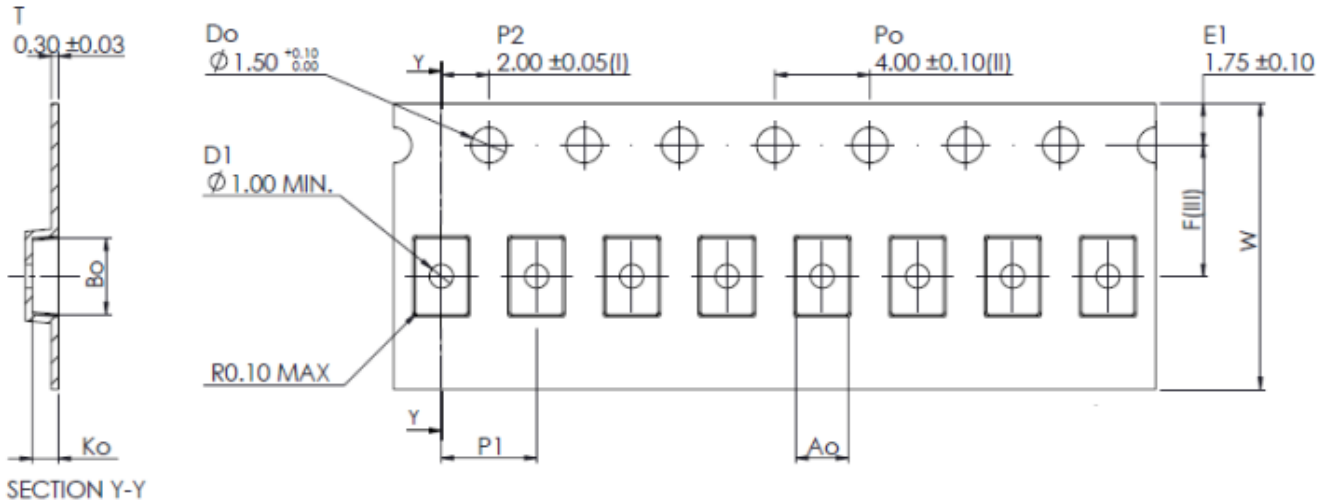


根据 EDEC-J-STD-020E 内容，参考以下内容。  
Compatible with the JEDEC-J-STD-020E, using the parameters listed below.

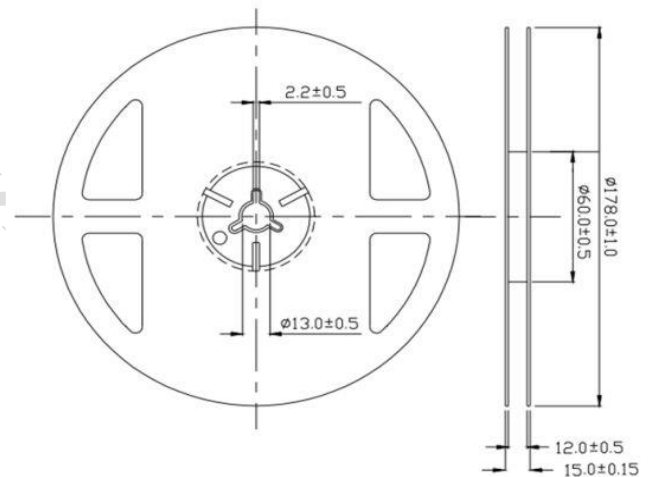
| 特制参数 Profile Feature  | 无铅焊料 Lead-Free Solder |
|---|-----------------------|
| 平均上升速率 (T <sub>Smax</sub> 至 T <sub>P</sub> )<br>Average Ramp-Up Rate (T <sub>Smax</sub> to T <sub>P</sub> ) | 3 °C/sec max.         |
| 预热: 温度最小值 (T <sub>Smin</sub> )<br>Preheat: Temperature Min (T <sub>Smin</sub> )                             | 150                   |
| 预热: 最高温度 (T <sub>Smax</sub> )<br>Preheat: Temperature Max (T <sub>Smax</sub> )                              | 200                   |
| 预热: 时间 (t <sub>Smin</sub> 到 t <sub>Smax</sub> )<br>Preheat: Time (t <sub>Smin</sub> to t <sub>Smax</sub> )  | 60-180 secs           |
| 回流温度 (T <sub>L</sub> )<br>Time Maintained Above: Temperature (T <sub>L</sub> )                              | 217°C                 |
| 回流时间 (t <sub>L</sub> )<br>Time Maintained Above: Time (t <sub>L</sub> )                                     | 60-150 secs           |
| 峰值/分类温度 (T <sub>P</sub> )<br>Peak/Classification Temperature (T <sub>P</sub> )                              | 255 ± 5°C             |
| 实际峰值温度 (t <sub>p</sub> ) 在 5°C 以内的时间<br>Time Within 5°C of Actual Peak Temperature (t <sub>p</sub> )        | 20~40 secs            |
| 降低速率<br>Ramp-Down Rate  | 4°C/sec max.          |



### 9、载带及卷轴 Reel Dimensions



|    |                    |
|----|--------------------|
| Ao | 2.20 +/- 0.05      |
| Bo | 3.20 +/- 0.05      |
| Ko | 1.10 +/- 0.05      |
| F  | 5.50 +/- 0.05      |
| P1 | 4.00 +/- 0.10      |
| W  | 12.00 +0.30/- 0.10 |



备注 Notes:

- ◇ 卷轴包装 3000pcs  
Reel:3000pcs.
- ◇ 卷轴包装方法符合 IJSC0806 (连续胶带上的电子元件包装)  
The tape packing method complies with IJSC0806(Packing of Electronic Components on Continuous Tapes).
- ◇ 当卷轴由于工作中断而重绕时, 载带上压力不应超过 10N, 否则 LED 可能会粘在盖带上  
When the tape is rewound due to work interruptions, no more than 10N should be applied to the embossed carrier tape.  
The LEDs may stick to the cover tape.

## 10、可靠性 Reliability

### a) 测试和结果 Tests and Results

| 测试项目<br>Test Item                                    | 标准<br>Reference Standard | 测试条件<br>Test Conditions   | 测试周期<br>Test Duration            | 失效标准<br>Failure Criteria# |
|--|--------------------------|---|----------------------------------|---------------------------|
| 外观检测<br>External Visual                              | JESD22 B-101             | Visual Inspection   | /                                | #1                        |
| 破坏性物理分析<br>D.P.A                                     | AEC-Q102                 | Random Sample HSTRB,HAST,TC   | /                                | #1                        |
| 振动<br>Vibration                                      | JESD22 B-103             | 0.06 inch displacement,20 to 100 Hz,50 g 100 Hz to 2kHz,  | 4times                           | #1                        |
| 静电测试<br>ESD  | JESD22 A-114             | Human-body mode,<br>R = 1.5 k $\Omega$ , C = 100pF  | 3 times<br>Negative/<br>Positive | #1                        |
| 机械冲击<br>Mechanical Shock                             | JESD22 B-104             | 1500 g's for 0.5 ms,<br>5 blows, 3 orientations   | 3times                           | #1                        |
| 常温测试<br>Life Teat                                    | JESD22 A-108             | 25°C, 1000 hours @250mA   | 1000hrs                          | #1                        |
| 温度循环<br>Power Temperature<br>Cycle                   | JESD22 A-105             | Ta = -40°C~ 85°C, If = 200mA,<br>20 min dwell / 20 min transition (1<br>hour cycle), 2 min ON / 2 min OFF | 1000hrs                          | #1                        |
| 高温高湿测试<br>High Humidity High<br>Temp. Operating Life | JESD22 A-101             | 85°C/85% RH, @ 200mA  | 1000hrs                          | #1                        |
| 高温老化<br>High Temperature<br>Operating Life           | JESD22 A-108C            | Ts = 120°C, If = 250mA  | 1000hrs                          | #1                        |
| 低温老化<br>Low Temperature<br>Operating Life            | JESD22 A-108C            | Ta = -40°C, If =200mA   | 1000hrs                          | #1                        |
| 低温储存<br>Low Temperature<br>Storage Life              | JESD22 A-119             | Ta = -40°C, non-operating   | 1000hrs                          | #1                        |
| 高温储存<br>Hight Temperature<br>Storage Life            | JESD22 A-103B            | Ta = 125°C, non-operating   | 1000hrs                          | #1                        |
| 冷热冲击<br>Thermal Shock                                | JESD22 A-104             | -40°C ~ 125°C, 1000 cycles  | 1000cycles                       | #1                        |





## b) 失效标准 Failure Criteria

| Criteria # | Items                      | Conditions | Failure Criteria  |
|------------|----------------------------|------------|---|
| #1         | Forward Voltage ( $V_F$ )  | $I_F$      | $> \text{Initial value} \times 1.1$ or<br>$< \text{Initial value} \times 0.9$ |
|            | Luminous Flux ( $\Phi_v$ ) | $I_F$      | $< \text{Initial value} \times 0.7$   |

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## 11、注意事项 Cautions

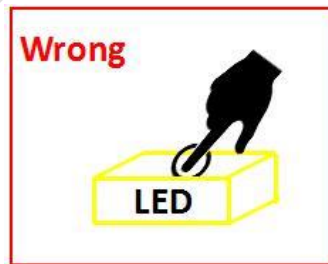
### a) 存储 Storage

- 不要将芯片放在潮湿的地方，存放温度在 5°C~30°C之间，相对湿度在 30%以下。  
Do not place the chips in damp places, Storage temperature between 5 °C and 30 °C, Relative humidity under 30%.
- 开包后建议在 24 小时内过完回流焊，车间条件≤30°C/60%RH。  
After opening the package, it is recommended to finish the reflow within 24 hours. The workshop conditions are ≤30°C/60%RH
- 如果受潮，需将贴片卷盘放入 60°C烤箱烘烤 24 小时；打开后，LED 灯可重新密封在原始真空袋中。  
If it is wet, the patch reel should be baked in a 60 ° C oven for 24 hours; after opening, the LED light can be resealed in the original vacuum bag.
- 不要接触任何未知的液体，特别是丙酮。  
Don't touch any unknown liquid, In particular, acetone.
- 防止静电死亡，手动操作需要戴橡胶手套并佩戴静电环。  
Prevent electrostatic killed, Manual operation is required to wear rubber gloves and wear electrostatic ring.

### b) 清洗 Cleaning

- 通常，LED 不建议对部件进行湿式清洁处理，因为封装不是密封的。  
In general, LED does not recommend a wet cleaning process for component as the package is not hermetically sealed.
- 由于采用开放式设计，所有类型的清洁液都可能渗透到封装中，导致 LED 退化或完全失效。  
Due to the open design, all kind of cleaning liquids can infiltrate the package and cause a degradation or a complete failure of the LED.

### c) 操作注意 Handling Precautions



- 在处理过程中，还应注意确保组件顶面没有压力。  
During the handling, care should be taken as well to ensure no pressure on the top surface of component.
- 应避免使用所有类型的尖锐物体（例如镊子，指甲等），以防止对硅树脂造成压力，因为这会导致部件损坏。  
All types of sharp objects(e.g. forceps, fingernail, etc) should be avoided in order to prevent stress to the silicone, since this can lead to damage of the component.

## 12、文件履历表 Document Resume

| 序号 | 变更日期       | 变更人 | 版本  | 变更内容   |
|----|------------|-----|-----|--|
| 01 | 2023.07.15 | 曾海强 | Y00 | 1.新制定;   |
| 02 | 2023.7.31  | 曾海强 | A00 | 1.更新产品图片;  |
| 03 | 2024.03.09 | 李俊杰 | A01 | 1. 删除最小正向电流信息;<br>2. 新增 CX1 色区;<br>3. 新增 LED 质量信息; |
|    |            |     |     |  |
|    |            |     |     |  |
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